

In re Patent Application of:

**VINSON ET AL.**

Serial No. 09/915,762

Filing Date: July 26, 2001

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**In the Claims:**

1. (ONCE AMENDED) An integrated circuit chip module comprising:

- a substrate;
- an integrated circuit die mounted on the substrate and having die pads and an exposed surface opposite from the substrate;
- a plurality of substrate bonding pads positioned on the substrate adjacent the integrated circuit die; and
- a at least one decoupling capacitor assembly mounted on each the integrated circuit die, said decoupling capacitor assembly comprising
  - a capacitor carrier secured onto the exposed surface of the integrated circuit die, and
  - a decoupling capacitor carried by the capacitor carrier; and
  - a wire bond extending from the decoupling capacitor assembly to a the die pads and from a the die pads to a the substrate bonding pads.

2. (original)

3. (original)

4. (original)

5. (original)

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6. (original)

7. (original)

8. (ONCE AMENDED) An integrated circuit chip module according to Claim 1, wherein a the wire bond extends from said decoupling capacitor to a logic pin of said integrated circuit die.

Claims 9-18 (CANCELLED)

19. (ONCE AMENDED) A multi-chip module comprising:  
a ceramic substrate;  
a plurality of integrated circuit die mounted on the ceramic substrate, each integrated circuit die including die pads and an exposed surface opposite from the ceramic substrate;  
a plurality of substrate bonding pads mounted on the substrate adjacent the plurality of integrated circuit die;  
and  
a plurality of decoupling capacitor assemblies positioned on each integrated circuit die, each decoupling capacitor assembly comprising  
an aluminum nitride capacitor carrier secured onto the exposed surface of the integrated circuit die, and  
a decoupling capacitor carried by the capacitor carrier; and

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at least one wire bond extending from each decoupling capacitor assembly to a the logic pin and from a the logic pin to a the substrate bonding pad.

20. (original)

21. (original)

22. (CANCELLED)

23. (original)

24. (original)

25. (original)

26. (original)

27. (original)

28. (original)

29. (CANCELLED)

30. (CANCELLED)

31. (original)

Claims 32-37 (CANCELLED)